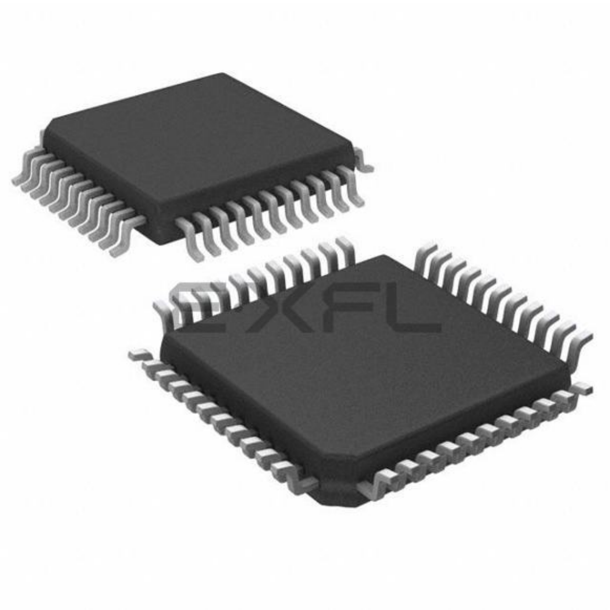
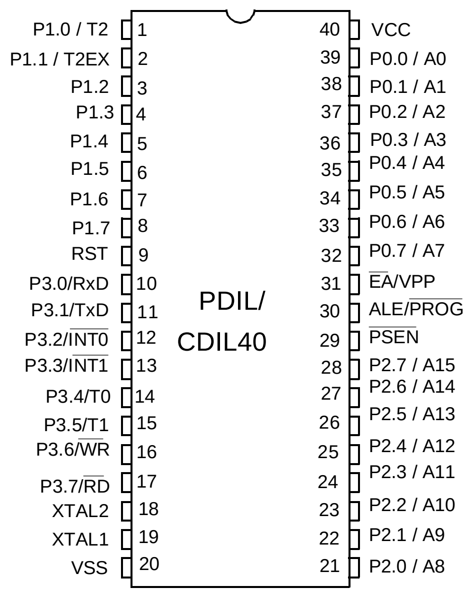
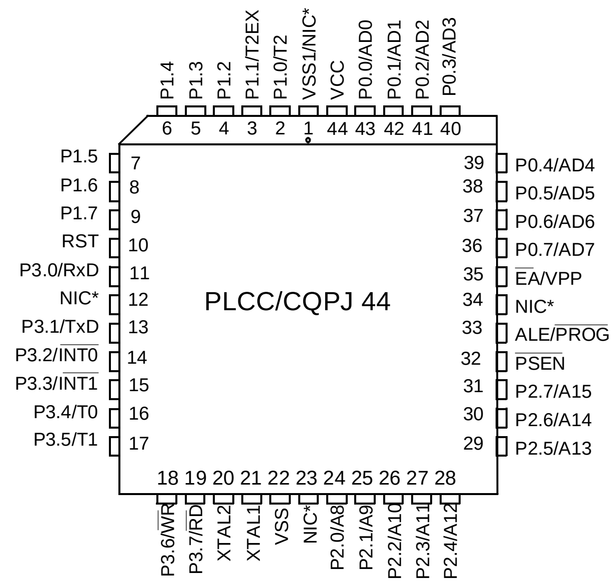
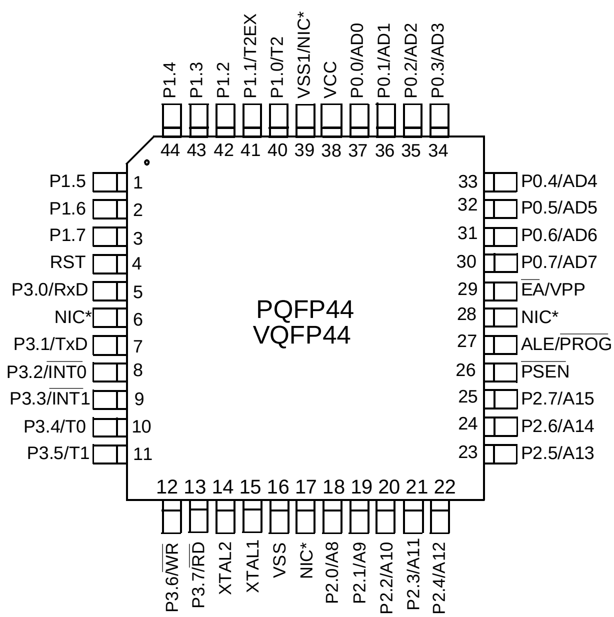


Details	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	60/30MHz
Connectivity	UART/USART
Peripherals	POR
Number of I/O	32
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-QFP
Supplier Device Package	44-PQFP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts80c32x2-vic

Pin Configuration







*NIC: No Internal Connection

Mnemonic	Pin Number			Type	Name and Function
	DIL	LCC	VQFP 1.4		
	13	15	9	I	**INT1 (P3.3):** External interrupt 1
	14	16	10	I	**T0 (P3.4):** Timer 0 external input
	15	17	11	I	**T1 (P3.5):** Timer 1 external input
	16	18	12	O	**WR (P3.6):** External data memory write strobe
	17	19	13	O	**RD (P3.7):** External data memory read strobe
Reset	9	10	4	I	**Reset:** A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V_{SS} permits a power-on reset using only an external capacitor to $V_{CC.}$
ALE/PROG	30	33	27	O (I)	**Address Latch Enable/Program Pulse:** Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted at a constant rate of 1/6 (1/3 in X2 mode) the oscillator frequency, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. This pin is also the program pulse input (PROG) during EPROM programming. ALE can be disabled by setting SFR's AUXR.0 bit. With this bit set, ALE will be inactive during internal fetches.
PSEN	29	32	26	O	**Program Store ENable:** The read strobe to external program memory. When executing code from the external program memory, PSEN is activated twice each machine cycle, except that two PSEN activations are skipped during each access to external data memory. PSEN is not activated during fetches from internal program memory.
EA/V_{PP}	31	35	29	I	**External Access Enable/Programming Supply Voltage:** EA must be externally held low to enable the device to fetch code from external program memory locations 0000H and 3FFFH (RB) or 7FFFH (RC), or FFFFH (RD). If EA is held high, the device executes from internal program memory unless the program counter contains an address greater than 3FFFH (RB) or 7FFFH (RC) EA must be held low for ROMless devices. This pin also receives the 12.75V programming supply voltage (V_{PP}) during EPROM programming. If security level 1 is programmed, EA will be internally latched on Reset.
XTAL1	19	21	15	I	**Crystal 1:** Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
XTAL2	18	20	14	O	**Crystal 2:** Output from the inverting oscillator amplifier

Dual Data Pointer Register (Ddptr)

The additional data pointer can be used to speed up code execution and reduce code size in a number of ways.

The dual DPTR structure is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called
DPS = AUXR1/bit0 (See Table 5.) that allows the program code to switch between them (Refer to Figure 3).

Figure 3. Use of Dual Pointer

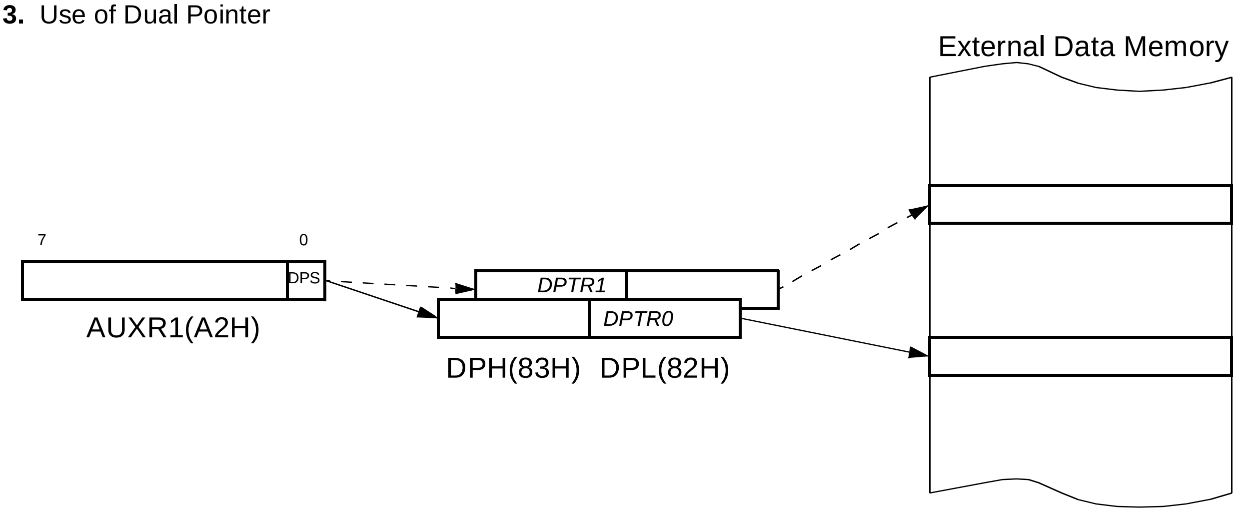


Table 4. AUXR1: Auxiliary Register 1

7	6	5	4	3	2	1	0
-	-	-	-	GF3	0	-	DPS

Bit Number	Bit Mnemonic	Description
7	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
6	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
5	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
4	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
3	GF3	This bit is a general purpose user flag
2	0	**Reserved** Always stuck at 0
1	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
0	DPS	**Data Pointer Selection** Clear to select DPTR0. Set to select DPTR1.

Reset Value = XXXX XXX0
Not bit addressable

Application

Software can take advantage of the additional data pointers to both increase speed and reduce code size, for example, block operations (copy, compare, search ...) are well served by using one data pointer as a 'source' pointer and the other one as a "destination" pointer.

ASSEMBLY LANGUAGE

```
; Block move using dual data pointers
; Destroys DPTR0, DPTR1, A and PSW
; note: DPS exits opposite of entry state
; unless an extra INC AUXR1 is added
;
00A2     AUXR1 EQU 0A2H
;
0000 909000MOV DPTR,#SOURCE ; address of SOURCE
0003 05A2 INC AUXR1 ; switch data pointers
0005 90A000 MOV DPTR,#DEST ; address of DEST
0008    LOOP:
0008 05A2 INC AUXR1 ; switch data pointers
000A E0 MOVX A,atDPTR ; get a byte from SOURCE
000B A3 INC DPTR ; increment SOURCE address
000C 05A2 INC AUXR1 ; switch data pointers
000E F0 MOVX atDPTR,A ; write the byte to DEST
000F A3 INC DPTR ; increment DEST address
0010 70F6JNZ LOOP ; check for 0 terminator
0012 05A2 INC AUXR1 ; (optional) restore DPS
```

INC is a short (2 bytes) and fast (12 clocks) way to manipulate the DPS bit in the AUXR1 SFR. However, note that the INC instruction does not directly force the DPS bit to a particular state, but simply toggles it. In simple routines, such as the block move example, only the fact that DPS is toggled in the proper sequence matters, not its actual value. In other words, the block move routine works the same whether DPS is '0' or '1' on entry. Observe that without the last instruction (INC AUXR1), the routine will exit with DPS in the opposite state.

Table 9. SCON Register

SCON - Serial Control Register (98h)

7	6	5	4	3	2	1	0
FE/SM0	SM1	SM2	REN	TB8	RB8	TI	RI

Bit Number	Bit Mnemonic	Description
7	FE	**Framing Error bit (SMOD0=1)** Clear to reset the error state, not cleared by a valid stop bit. Set by hardware when an invalid stop bit is detected. SMOD0 must be set to enable access to the FE bit
	SM0	**Serial port Mode bit 0** Refer to SM1 for serial port mode selection. SMOD0 must be cleared to enable access to the SM0 bit
6	SM1	**Serial port Mode bit 1** SM0 SM1 Mode Description Baud Rate 0 0 0 Shift Register F_{XTAL}/12 (/6 in X2 mode) 0 1 1 8-bit UART Variable 1 0 2 9-bit UART F_{XTAL}/64 or F_{XTAL}/32 (/32, /16 in X2 mode) 1 1 3 9-bit UART Variable
5	SM2	**Serial port Mode 2 bit / Multiprocessor Communication Enable bit** Clear to disable multiprocessor communication feature. Set to enable multiprocessor communication feature in mode 2 and 3, and eventually mode 1. This bit should be cleared in mode 0.
4	REN	**Reception Enable bit** Clear to disable serial reception. Set to enable serial reception.
3	TB8	Transmitter Bit 8 / Ninth bit to transmit in modes 2 and 3. Clear to transmit a logic 0 in the 9th bit. Set to transmit a logic 1 in the 9th bit.
2	RB8	**Receiver Bit 8 / Ninth bit received in modes 2 and 3** Cleared by hardware if 9th bit received is a logic 0. Set by hardware if 9th bit received is a logic 1. In mode 1, if SM2 = 0, RB8 is the received stop bit. In mode 0 RB8 is not used.
1	TI	**Transmit Interrupt flag** Clear to acknowledge interrupt. Set by hardware at the end of the 8th bit time in mode 0 or at the beginning of the stop bit in the other modes.
0	RI	**Receive Interrupt flag** Clear to acknowledge interrupt. Set by hardware at the end of the 8th bit time in mode 0, see Figure 7. and Figure 8. in the other modes.

Reset Value = 0000 0000b
Bit addressable

Table 10. PCON Register

PCON - Power Control Register (87h)

7	6	5	4	3	2	1	0
SMOD1	SMOD0	-	POF	GF1	GF0	PD	IDL

Bit Number	Bit Mnemonic	Description
7	SMOD1	**Serial port Mode bit 1** Set to select double baud rate in mode 1, 2 or 3.
6	SMOD0	**Serial port Mode bit 0** Clear to select SM0 bit in SCON register. Set to to select FE bit in SCON register.
5	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
4	POF	**Power-off Flag** Clear to recognize next reset type. Set by hardware when VCC rises from 0 to its nominal voltage. Can also be set by software.
3	GF1	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
2	GF0	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
1	PD	**Power-down mode bit** Cleared by hardware when reset occurs. Set to enter power-down mode.
0	IDL	**Idle mode bit** Clear by hardware when interrupt or reset occurs. Set to enter idle mode.

Reset Value = 00X1 0000b
Not bit addressable

Power-off flag reset value will be 1 only after a power on (cold reset). A warm reset doesn't affect the value of this bit.

are received simultaneously, an internal polling sequence determines which request is serviced. Thus within each priority level there is a second priority structure determined by the polling sequence.

Table 12. IE Register
IE - Interrupt Enable Register (A8h)

7	6	5	4	3	2	1	0
EA	-	ET2	ES	ET1	EX1	ET0	EX0

Bit Number	Bit Mnemonic	Description
7	EA	**Enable All interrupt bit** Clear to disable all interrupts. Set to enable all interrupts. If EA=1, each interrupt source is individually enabled or disabled by setting or clearing its own interrupt enable bit.
6	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
5	ET2	**Timer 2 overflow interrupt Enable bit** Clear to disable timer 2 overflow interrupt. Set to enable timer 2 overflow interrupt.
4	ES	**Serial port Enable bit** Clear to disable serial port interrupt. Set to enable serial port interrupt.
3	ET1	**Timer 1 overflow interrupt Enable bit** Clear to disable timer 1 overflow interrupt. Set to enable timer 1 overflow interrupt.
2	EX1	**External interrupt 1 Enable bit** Clear to disable external interrupt 1. Set to enable external interrupt 1.
1	ET0	**Timer 0 overflow interrupt Enable bit** Clear to disable timer 0 overflow interrupt. Set to enable timer 0 overflow interrupt.
0	EX0	**External interrupt 0 Enable bit** Clear to disable external interrupt 0. Set to enable external interrupt 0.

Reset Value = 0X00 0000b
Bit addressable

ONCE^{TM} Mode (ON Chip Emulation)

The ONCE mode facilitates testing and debugging of systems using TS80C52X2 without removing the circuit from the board. The ONCE mode is invoked by driving certain pins of the TS80C52X2; the following sequence must be exercised:

- Pull ALE low while the device is in reset (RST high) and $\overline{\text{PSEN}}$ is high.
- Hold ALE low as RST is deactivated.

While the TS80C52X2 is in ONCE mode, an emulator or test CPU can be used to drive the circuit Table 26. shows the status of the port pins during ONCE mode.

Normal operation is restored when normal reset is applied.

Table 16. External Pin Status during ONCE Mode

ALE	PSEN	Port 0	Port 1	Port 2	Port 3	XTAL1/2
Weak pull-up	Weak pull-up	Float	Weak pull-up	Weak pull-up	Weak pull-up	Active

Reduced EMI Mode

The ALE signal is used to demultiplex address and data buses on port 0 when used with external program or data memory. Nevertheless, during internal code execution, ALE signal is still generated. In order to reduce EMI, ALE signal can be disabled by setting AO bit.

The AO bit is located in AUXR register at bit location 0. As soon as AO is set, ALE is no longer output but remains active during MOVX and MOVC instructions and external fetches. During ALE disabling, ALE pin is weakly pulled high.

Table 18. AUXR Register

AUXR - Auxiliary Register (8Eh)

7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	AO

Bit Number	Bit Mnemonic	Description
7	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
6	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
5	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
4	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
3	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
2	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
1	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
0	AO	**ALE Output bit** Clear to restore ALE operation during internal fetches. Set to disable ALE operation during internal fetches.

Reset Value = XXXX XXX0b
Not bit addressable

TS80C52X2

ROM Structure

The TS80C52X2 ROM memory is divided in three different arrays:

- the code array:8 Kbytes.
- the encryption array:64 bytes.
- the signature array:4 bytes.

ROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

Encryption Array

Within the ROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

Program Lock Bits

The lock bits when programmed according to Table 19. will provide different level of protection for the on-chip code and data.

Table 19. Program Lock bits

Program Lock Bits				
Security level	LB1	LB2	LB3	Protection Description
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	P	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset.

U: unprogrammed
P: programmed

Signature bytes

The TS80C52X2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 9.

Verify Algorithm

Refer to Section "Verify Algorithm".

EPROM Structure

The TS87C52X2 is divided in two different arrays:

- the code array: 8 Kbytes
- the encryption array: 64 bytes

In addition a third non programmable array is implemented:

- the signature array: 4 bytes

EPROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

Encryption Array

Within the EPROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

Program Lock Bits

The three lock bits, when programmed according to Table 1., will provide different level of protection for the on-chip code and data.

Program Lock Bits				
Security level	**LB1**	**LB2**	**LB3**	**Protection Description**
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	P	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset, and further programming of the EPROM is disabled.
3	U	P	U	Same as 2, also verify is disabled.
4	U	U	P	Same as 3, also external execution is disabled.

U: unprogrammed
P: programmed

WARNING: Security level 2 and 3 should only be programmed after EPROM and Core verification.

Signature Bytes

The TS80/87C52X2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 9.

EPROM Programming

Set-up modes

In order to program and verify the EPROM or to read the signature bytes, the TS87C52X2 is placed in specific set-up modes (See Figure 11.).

Control and program signals must be held at the levels indicated in Table 35.

Definition of terms

Address Lines: P1.0-P1.7, P2.0-P2.4 respectively for A0-A12

Data Lines: P0.0-P0.7 for D0-D7

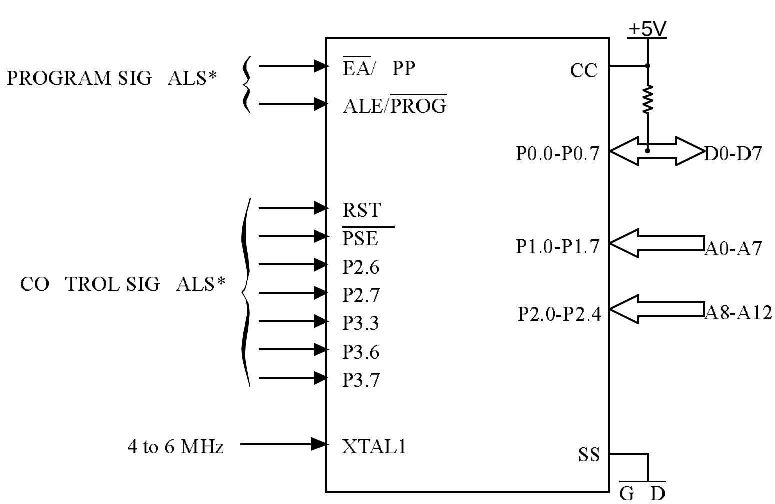
Control Signals: RST, $\overline{\text{PSEN}}$, P2.6, P2.7, P3.3, P3.6, P3.7.

Program Signals: ALE/$\overline{\text{PROG}}$, $\overline{\text{EA}}$/VPP.

Table 20. EPROM Set-up Modes

Mode	RST	PSEN	ALE/ $\overline{\text{PROG}}$	$\overline{\text{EA}}$/ VPP	P2.6	P2.7	P3.3	P3.6	P3.7
Program Code data	1	0	⊔	12.75V	0	1	1	1	1
Verify Code data	1	0	1	1	0	⊔	0	1	1
Program Encryption Array Address 0-3Fh	1	0	⊔	12.75V	0	1	1	0	1
Read Signature Bytes	1	0	1	1	0	⊔	0	0	0
Program Lock bit 1	1	0	⊔	12.75V	1	1	1	1	1
Program Lock bit 2	1	0	⊔	12.75V	1	1	1	0	0
Program Lock bit 3	1	0	⊔	12.75V	1	0	1	1	0

Figure 11. Set-Up Modes Configuration



* See Table 31. for proper value on these inputs

Electrical Characteristics

Absolute Maximum Ratings[1]

Ambiant Temperature Under Bias:
C = commercial ....0°C to 70°C
I = industrial ....-40°C to 85°C
Storage Temperature .... -65°C to + 150°C
Voltage on V_{CC} to V_{SS} ....-0.5V to + 7 V
Voltage on V_{PP} to V_{SS} ....-0.5V to + 13 V
Voltage on Any Pin to V_{SS}..........................-0.5V to V_{CC} + 0.5V
Power Dissipation .... 1 W[2]

Notes: 1. Stresses at or above those listed under " Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
2. This value is based on the maximum allowable die temperature and the thermal resistance of the package.

Power Consumption Measurement

Since the introduction of the first C51 devices, every manufacturer made operating Icc measurements under reset, which made sense for the designs were the CPU was running under reset. In Atmel new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel presents a new way to measure the operating Icc:

Using an internal test ROM, the following code is executed:

```
Label:          SJMP Label (80 FE)
```

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = Vcc, RST = Vss, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating Icc.

DC Parameters for Standard Voltage

TA = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5V ± 10%; F = 0 to 40 MHz.
TA = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 5V ± 10%; F = 0 to 40 MHz.

Table 22. DC Parameters in Standard Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3 [6]			0.3 0.45 1.0	V V V	I_{OL} = 100 μA[4] I_{OL} = 1.6 mA[4] I_{OL} = 3.5 mA[4]
V_{OL1}	Output Low Voltage, port 0 [6]			0.3 0.45 1.0	V V V	I_{OL} = 200 μA[4] I_{OL} = 3.2 mA[4] I_{OL} = 7.0 mA[4]
V_{OL2}	Output Low Voltage, ALE, $\overline{PSEN}$			0.3 0.45 1.0	V V V	I_{OL} = 100 μA[4] I_{OL} = 1.6 mA[4] I_{OL} = 3.5 mA[4]

DC Parameters for Low Voltage

TA = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5V ; F = 0 to 30 MHz.
TA = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5V ; F = 0 to 30 MHz.

Table 23. DC Parameters for Low Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3 (6)			0.45	V	I_{OL} = 0.8 mA(4)
V_{OL1}	Output Low Voltage, port 0, ALE, $\overline{PSEN}$ (6)			0.45	V	I_{OL} = 1.6 mA(4)
V_{OH}	Output High Voltage, ports 1, 2, 3	0.9 V_{CC}			V	I_{OH} = -10 µA
V_{OH1}	Output High Voltage, port 0, ALE, $\overline{PSEN}$	0.9 V_{CC}			V	I_{OH} = -40 µA
I_{IL}	Logical 0 Input Current ports 1, 2 and 3			-50	µA	Vin = 0.45V
I_{LI}	Input Leakage Current			±10	µA	0.45V < Vin < V_{CC}
I_{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3			-650	µA	Vin = 2.0 V
R_{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
CIO	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz TA = 25°C
I_{PD}	Power Down Current		20 (5) 10 (5)	50 30	µA	V_{CC} = 2.0 V to 5.5V(3) V_{CC} = 2.0 V to 3.3 V(3)
I_{CC} under RESET	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.2 Freq (MHz) at12MHz 3.4 at16MHz 4.2	mA	V_{CC} = 3.3 V(1)
I_{CC} operating	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.3 Freq (MHz) at12MHz 4.6 at16MHz 5.8	mA	V_{CC} = 3.3 V(8)
I_{CC} idle	Power Supply Current Maximum values, X1 mode: (7)			0.15 Freq (MHz) + 0.2 at12MHz 2 at16MHz 2.6	mA	V_{CC} = 3.3 V(2)

Notes:
1. I_{CC} under reset is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 17.), V_{IL} = V_{SS} + 0.5V,
   V_{IH} = V_{CC} - 0.5V; XTAL2 N.C.; $\overline{EA}$ = RST = Port 0 = V_{CC}. I_{CC} would be slightly higher if a crystal oscillator used..
2. Idle I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns, V_{IL} = V_{SS} + 0.5V, V_{IH} = V_{CC} - 0.5V; XTAL2 N.C; Port 0 = V_{CC}; $\overline{EA}$ = RST = V_{SS} (see Figure 15.).
3. Power Down I_{CC} is measured with all output pins disconnected; $\overline{EA}$ = V_{SS}, PORT 0 = V_{CC}; XTAL2 NC.; RST = V_{SS} (see Figure 16.).
4. Capacitance loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL}s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1 to 0 transitions during bus operation. In the worst cases (capacitive loading 100pF), the noise pulse on the ALE line may exceed 0.45V with maxi V_{OL} peak 0.6V. A Schmitt Trigger use is not necessary.
5. Typicals are based on a limited number of samples and are not guaranteed. The values listed are at room temperature and 5V.
6. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 10 mA
   Maximum I_{OL} per 8-bit port:

Port 0: 26 mA
Ports 1, 2 and 3: 15 mA
Maximum total I_{OL} for all output pins: 71 mA
If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

7. For other values, please contact your sales office.
8. Operating I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 17.), V_{IL} = V_{SS} + 0.5V,
   V_{IH} = V_{CC} - 0.5V; XTAL2 N.C.; $\overline{EA}$ = Port 0 = V_{CC}; RST = V_{SS}. The internal ROM runs the code 80 FE (label: SJMP label). I_{CC} would be slightly higher if a crystal oscillator is used. Measurements are made with OTP products when possible, which is the worst case.

Figure 13. I_{CC} Test Condition, under reset

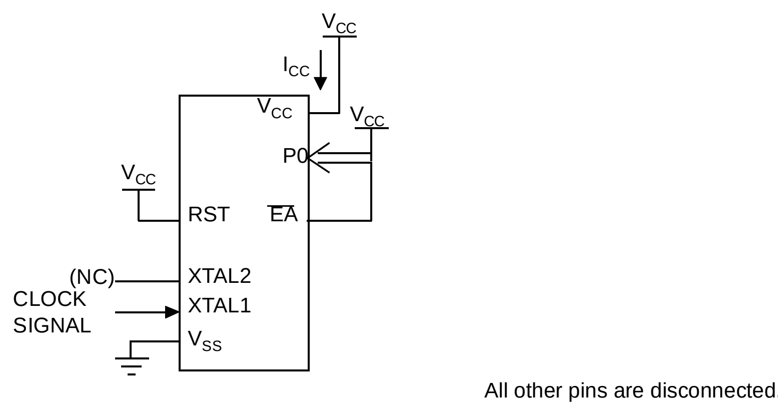


Figure 14. Operating I_{CC} Test Condition

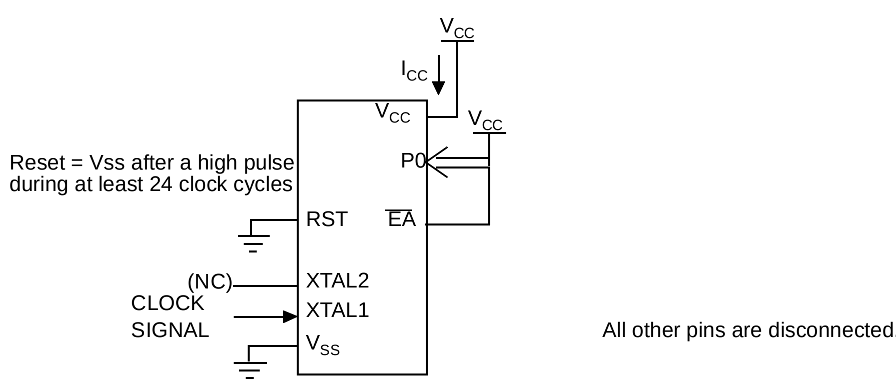


Figure 15. I_{CC} Test Condition, Idle Mode

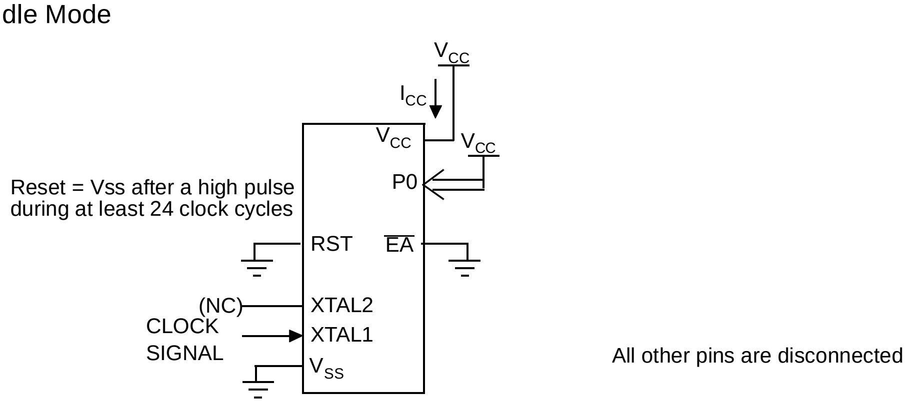
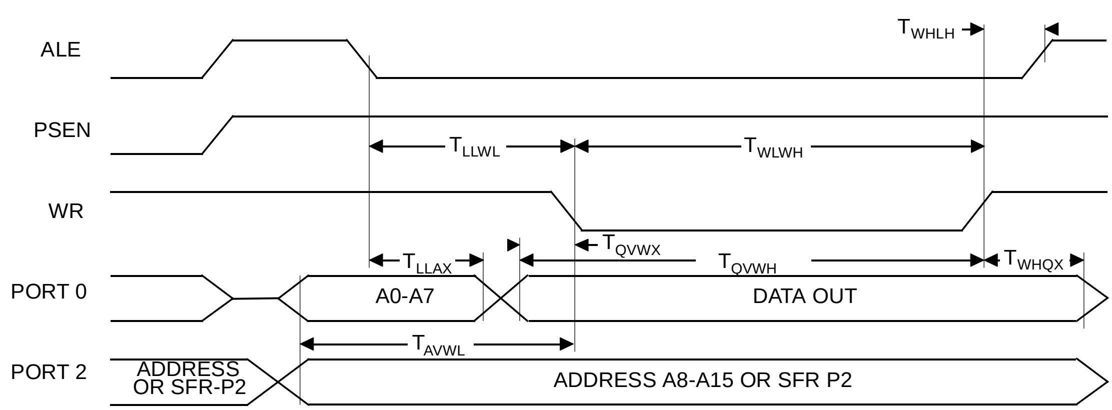


Table 31. AC Parameters for a Variable Clock: Derating Formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{RLRH}	Min	6 T - x	3 T - x	20	15	25	ns
T_{WLWH}	Min	6 T - x	3 T - x	20	15	25	ns
T_{RLDV}	Max	5 T - x	2.5 T - x	25	23	30	ns
T_{RHDX}	Min	x	x	0	0	0	ns
T_{RHDZ}	Max	2 T - x	T - x	20	15	25	ns
T_{LLDV}	Max	8 T - x	4T -x	40	35	45	ns
T_{AVDV}	Max	9 T - x	4.5 T - x	60	50	65	ns
T_{LLWL}	Min	3 T - x	1.5 T - x	25	20	30	ns
T_{LLWL}	Max	3 T + x	1.5 T + x	25	20	30	ns
T_{AVWL}	Min	4 T - x	2 T - x	25	20	30	ns
T_{QVWX}	Min	T - x	0.5 T - x	15	10	20	ns
T_{QVWH}	Min	7 T - x	3.5 T - x	15	10	20	ns
T_{WHQX}	Min	T - x	0.5 T - x	10	8	15	ns
T_{RLAZ}	Max	x	x	0	0	0	ns
T_{WHLH}	Min	T - x	0.5 T - x	15	10	20	ns
T_{WHLH}	Max	T + x	0.5 T + x	15	10	20	ns

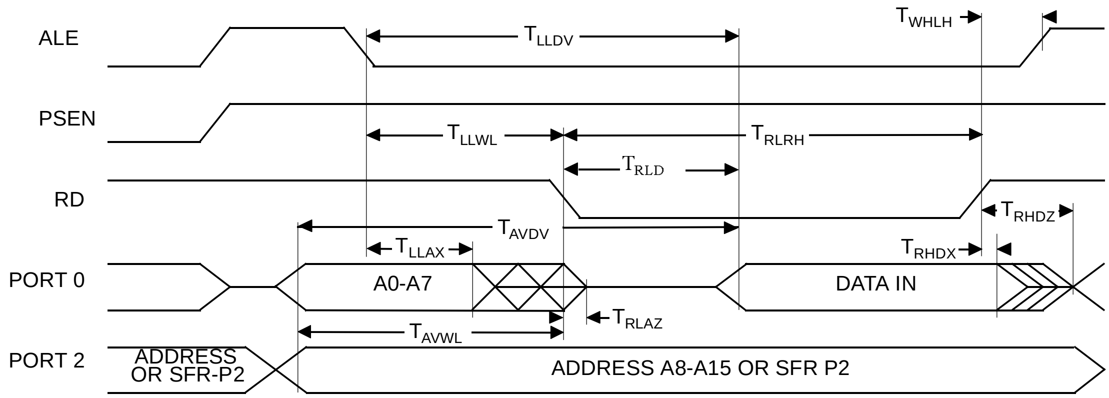
External Data Memory Write Cycle

Figure 19. External Data Memory Write Cycle



External Data Memory Read Cycle

Figure 20. External Data Memory Read Cycle



Serial Port Timing - Shift Register Mode

Table 32. Symbol Description

Symbol	Parameter
T_{XLXL}	Serial port clock cycle time
T_{QVHX}	Output data set-up to clock rising edge
T_{XHQX}	Output data hold after clock rising edge
T_{XHDX}	Input data hold after clock rising edge
T_{XHDV}	Clock rising edge to input data valid

Table 33. AC Parameters for a Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
T_{XLXL}	300		200		300		300		400		ns
T_{QVHX}	200		117		200		200		283		ns
T_{XHQX}	30		13		30		30		47		ns
T_{XHDX}	0		0		0		0		0		ns
T_{XHDV}		117		34		117		117		200	ns

Table 37. Possible Ordering Entries (Continued)

Part Number[(3)]	Memory Size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
AT80C32X2-RLTUL	ROMLess	2.7 to 5.5V	Industrial & Green	30 MHz[(1)]	VQFP44	Tray
AT80C32X2-3CSUV	ROMLess	5V ±10%	Industrial & Green	60 MHz[(3)]	PDIL40	Stick
AT80C32X2-SLSUV	ROMLess	5V ±10%	Industrial & Green	60 MHz[(3)]	PLCC44	Stick
AT80C32X2-RLTUV	ROMLess	5V ±10%	Industrial & Green	60 MHz[(3)]	VQFP44	Tray
TS80C52X2zzz-MCA	8K ROM	2.7 to 5.5V	Commercial	40 MHz[(1)]	PDIL40	Stick
TS80C52X2zzz-MCB	8K ROM	2.7 to 5.5V	Commercial	40 MHz[(1)]	PLCC44	Stick
TS80C52X2zzz-MCC	8K ROM	2.7 to 5.5V	Commercial	40 MHz[(1)]	PQFP44	Tray
TS80C52X2zzz-MCE	8K ROM	2.7 to 5.5V	Commercial	40 MHz[(1)]	VQFP44	Tray
TS80C52X2zzz-LCA	8K ROM	2.7 to 5.5V	Commercial	30 MHz[(1)]	PDIL40	Stick
TS80C52X2zzz-LCB	8K ROM	2.7 to 5.5V	Commercial	30 MHz[(1)]	PLCC44	Stick
TS80C52X2zzz-LCC	8K ROM	2.7 to 5.5V	Commercial	30 MHz[(1)]	PQFP44	Tray
TS80C52X2zzz-LCE	8K ROM	2.7 to 5.5V	Commercial	30 MHz[(1)]	VQFP44	Tray
TS80C52X2zzz-VCA	8K ROM	5V ±10%	Commercial	60 MHz[(3)]	PDIL40	Stick
TS80C52X2zzz-VCB	8K ROM	5V ±10%	Commercial	60 MHz[(3)]	PLCC44	Stick
TS80C52X2zzz-VCC	8K ROM	5V ±10%	Commercial	60 MHz[(3)]	PQFP44	Tray
TS80C52X2zzz-VCE	8K ROM	5V ±10%	Commercial	60 MHz[(3)]	VQFP44	Tray
TS80C52X2zzz-MIA	8K ROM	5V ±10%	Industrial	40 MHz[(1)]	PDIL40	Stick
TS80C52X2zzz-MIB	8K ROM	5V ±10%	Industrial	40 MHz[(1)]	PLCC44	Stick
TS80C52X2zzz-MIC	8K ROM	5V ±10%	Industrial	40 MHz[(1)]	PQFP44	Tray
TS80C52X2zzz-MIE	8K ROM	5V ±10%	Industrial	40 MHz[(1)]	VQFP44	Tray
TS80C52X2zzz-LIA	8K ROM	2.7 to 5.5V	Industrial	30 MHz[(1)]	PDIL40	Stick
TS80C52X2zzz-LIB	8K ROM	2.7 to 5.5V	Industrial	30 MHz[(1)]	PLCC44	Stick
TS80C52X2zzz-LIC	8K ROM	2.7 to 5.5V	Industrial	30 MHz[(1)]	PQFP44	Tray
TS80C52X2zzz-LIE	8K ROM	2.7 to 5.5V	Industrial	30 MHz[(1)]	VQFP44	Tray
TS80C52X2zzz-VIA	8K ROM	5V ±10%	Industrial	60 MHz[(3)]	PDIL40	Stick
TS80C52X2zzz-VIB	8K ROM	5V ±10%	Industrial	60 MHz[(3)]	PLCC44	Stick
TS80C52X2zzz-VIC	8K ROM	5V ±10%	Industrial	60 MHz[(3)]	PQFP44	Tray
TS80C52X2zzz-VIE	8K ROM	5V ±10%	Industrial	60 MHz[(3)]	VQFP44	Tray
AT80C52X2zzz-3CSUM	8K ROM	5V ±10%	Industrial & Green	40 MHz[(1)]	PDIL40	Stick
AT80C52X2zzz-SLSUM	8K ROM	5V ±10%	Industrial & Green	40 MHz[(1)]	PLCC44	Stick
AT80C52X2zzz-RLTUM	8K ROM	5V ±10%	Industrial & Green	40 MHz[(1)]	VQFP44	Tray

Table 37. Possible Ordering Entries (Continued)

Part Number[3]	Memory Size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
AT80C52X2zzz-3CSUL	8K ROM	2.7 to 5.5V	Industrial & Green	30 MHz[1]	PDIL40	Stick
AT80C52X2zzz-SLSUL	8K ROM	2.7 to 5.5V	Industrial & Green	30 MHz[1]	PLCC44	Stick
AT80C52X2zzz-RLTUL	8K ROM	2.7 to 5.5V	Industrial & Green	30 MHz[1]	VQFP44	Tray
AT80C52X2zzz-3CSUV	8K ROM	5V ±10%	Industrial & Green	60 MHz[3]	PDIL40	Stick
AT80C52X2zzz-SLSUV	8K ROM	5V ±10%	Industrial & Green	60 MHz[3]	PLCC44	Stick
AT80C52X2zzz-RLTUV	8K ROM	5V ±10%	Industrial & Green	60 MHz[3]	VQFP44	Tray
TS87C52X2-MCA	8K OTP	5V ±10%	Commercial	40 MHz[1]	PDIL40	Stick
TS87C52X2-MCB	8K OTP	5V ±10%	Commercial	40 MHz[1]	PLCC44	Stick
TS87C52X2-MCC	8K OTP	5V ±10%	Commercial	40 MHz[1]	PQFP44	Tray
TS87C52X2-MCE	8K OTP	5V ±10%	Commercial	40 MHz[1]	VQFP44	Tray
TS87C52X2-LCA	8K OTP	2.7 to 5.5V	Commercial	30 MHz[1]	PDIL40	Stick
TS87C52X2-LCB	8K OTP	2.7 to 5.5V	Commercial	30 MHz[1]	PLC44	Stick
TS87C52X2-LCC	8K OTP	2.7 to 5.5V	Commercial	30 MHz[1]	PQFP44	Tray
TS87C52X2-LCE	8K OTP	2.7 to 5.5V	Commercial	30 MHz[1]	VQFP44	Tray
TS87C52X2-VCA	8K OTP	5V ±10%	Commercial	60 MHz[3]	PDIL40	Stick
TS87C52X2-VCB	8K OTP	5V ±10%	Commercial	60 MHz[3]	PLCC44	Stick
TS87C52X2-VCC	8K OTP	5V ±10%	Commercial	60 MHz[3]	PQFP44	Tray
TS87C52X2-VCE	8K OTP	5V ±10%	Commercial	60 MHz[3]	VQFP44	Tray
TS87C52X2-MIA	8K OTP	5V ±10%	Industrial	40 MHz[1]	PDIL40	Stick
TS87C52X2-MIB	8K OTP	5V ±10%	Industrial	40 MHz[1]	PLCC44	Stick
TS87C52X2-MIC	8K OTP	5V ±10%	Industrial	40 MHz[1]	PQFP44	Tray
TS87C52X2-MIE	8K OTP	5V ±10%	Industrial	40 MHz[1]	VQFP44	Tray
TS87C52X2-LIA	8K OTP	2.7 to 5.5V	Industrial	30 MHz[1]	PDIL40	Stick
TS87C52X2-LIB	8K OTP	2.7 to 5.5V	Industrial	30 MHz[1]	PLCC44	Stick
TS87C52X2-LIC	8K OTP	2.7 to 5.5V	Industrial	30 MHz[1]	PQFP44	Tray
TS87C52X2-LIE	8K OTP	2.7 to 5.5V	Industrial	30 MHz[1]	VQFP44	Tray
TS87C52X2-VIA	8K OTP	5V ±10%	Industrial	60 MHz[3]	PDIL40	Stick
TS87C52X2-VIB	8K OTP	5V ±10%	Industrial	60 MHz[3]	PLCC44	Stick
TS87C52X2-VIC	8K OTP	5V ±10%	Industrial	60 MHz[3]	PQFP44	Tray
TS87C52X2-VIE	8K OTP	5V ±10%	Industrial	60 MHz[3]	VQFP44	Tray

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